

**Claim Amendments:**

1. (original): A disk drive write head comprising:
  - a bottom pole;
  - a write gap layer on said bottom pole;
  - a coil on said write gap layer;
  - a photoresist insulation layer on said coil;
  - an insulation shell layer on said photoresist insulation layer, the insulation shell layer being formed of a dielectric material having a lower milling rate than a milling rate of the photoresist insulation layer; and
  - a top pole on said insulation shell layer.
  
2. (original): The disk drive write head as recited in claim 1, wherein:
  - said insulation shell layer is formed by a process chosen from the group consisting of Physical Vapor Deposition (PVD), sputter deposition, ion beam deposition, Chemical Vapor Deposition (CVD), plasma enhanced Chemical Vapor Deposition (PECVD), Low Pressure Chemical Vapor Deposition (LPCVD) and Atomic Layer Chemical Vapor Deposition (ALCVD).
  
3. (original): The disk drive head as recited in claim 1, wherein:
  - said insulation shell layer is formed from materials chosen from the group consisting of dielectric materials,  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ ,  $\text{AlON}$ ,  $\text{SiO}_2$ ,  $\text{Si}_3\text{N}_4$ ,  $\text{SiON}$ ,  $\text{Ta}_2\text{O}_5$ , and  $\text{HfO}_2$ .

4. (original): The disk drive write head as recited in claim 1, wherein:  
said disk drive write head includes a read head.
5. (previously presented): A disk drive write head comprising:  
a bottom pole;  
a first insulation layer on said bottom pole;  
a coil on said first insulation layer;  
a photoresist insulation layer on said coil;  
an insulation shell layer on said photoresist insulation layer, said insulation shell layer conforming to the contours of said photoresist insulation layer, the insulation shell layer being formed of a dielectric material having a lower milling rate than a milling rate of the photoresist insulation layer;  
a write gap on said insulation shell layer; and  
a top pole on said write gap layer.
6. (original): The disk drive write head as recited in claim 5, wherein:  
said insulation shell layer is formed by a process chosen from the group consisting of Physical Vapor Deposition (PVD), sputter deposition, ion beam deposition, Chemical Vapor Deposition (CVD), plasma enhanced Chemical Vapor Deposition (PECVD), Low Pressure Chemical Vapor Deposition (LPCVD) and Atomic Layer Chemical Vapor Deposition (ALCVD).
7. (original): The disk drive write head as recited in claim 5, wherein:

said insulation shell layer is formed from materials chosen from the group consisting of dielectric materials,  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ ,  $\text{AlON}$ ,  $\text{SiO}_2$ ,  $\text{Si}_3\text{N}_4$ ,  $\text{SiON}$ ,  $\text{Ta}_2\text{O}_5$ , and  $\text{HfO}_2$ .

8. (original): The disk drive write head as recited in claim 5, wherein:

said disk drive write head includes a read head.

9. (cancelled)

10. (cancelled)

11. (cancelled)

12. (cancelled)

13. (cancelled)

14. (cancelled)

15. (cancelled)

16. (cancelled)

17. (original) A computer disk drive having a write head which includes a coil and a photoresist insulation layer on the coil, comprising:

an insulation shell layer on said photoresist insulation layer, the insulation shell layer being formed of a dielectric material having a lower milling rate than a milling rate of the photoresist insulation layer.

18. (original) A computer disk drive as recited in claim 17, further comprising:  
a top pole which is formed on said insulation shell layer.

19. (original) A computer disk drive as recited in claim 17, further comprising:  
a write gap on said insulation shell layer; and  
a top pole on said write gap layer.